

ABSTRACT

A semiconductor package includes a semiconductor chip provided with a plurality of electric terminals and a plurality of electrically conductive members electrically connected with the electric terminals. Connection terminals that are spherical in shape and made of solder are electrically connected with the electrically conductive members. A sealing member is used for sealing the semiconductor chip and the electrically conductive members, and for covering the connection terminals so as to allow a part thereof to be exposed. The electrically conductive members are provided with bonding promoters and are connected with the respective spherical connection terminals at the respective bonding promoters.